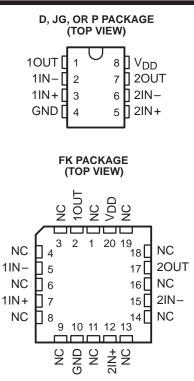
- Push-Pull CMOS Output Drives Capacitive Loads Without Pullup Resistor, I<sub>O</sub> = ± 8 mA
- Very Low Power ... 100 μW Typ at 5 V
- Fast Response Time . . . t<sub>PLH</sub> = 2.7 μs Typ With 5-mV Overdrive
- Single-Supply Operation ... 3 V to 16 V TLC3702M ... 4 V to 16 V
- On-Chip ESD Protection

### description

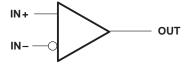
The TLC3702 consists of two independent micropower voltage comparators designed to operate from a single supply and be compatible with modern HCMOS logic systems. They are functionally similar to the LM339 but use onetwentieth of the power for similar response times. The push-pull CMOS output stage drives capacitive loads directly without a powerconsuming pullup resistor to achieve the stated response time. Eliminating the pullup resistor not only reduces power dissipation, but also saves board space and component cost. The output stage is also fully compatible with TTL requirements.

Texas Instruments LinCMOS<sup>™</sup> process offers superior analog performance to standard CMOS processes. Along with the standard CMOS advantages of low power without sacrificing speed, high input impedance, and low bias currents, the LinCMOS<sup>™</sup> process offers extremely stable input offset voltages with large differential input voltages. This characteristic makes it possible to build reliable CMOS comparators. SLCS013D - NOVEMBER 1986 - REVISED NOVEMBER 1998



NC - No internal connection

### symbol (each comparator)



The TLC3702C is characterized for operation over the commercial temperature range of 0°C to 70°C. The TLC3702I is characterized for operation over the extended industrial temperature range of –40°C to 85°C. The TLC3702M is characterized for operation over the full military temperature range of –55°C to 125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LinCMOS is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

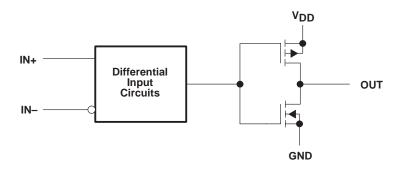


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AVAILABLE OPTIONS								
	Viemax		PACKA	GES				
TA	V <sub>IO</sub> max at 25°C	SMALL OUTLINE (D)	CERAMIC (FK)	CERAMIC DIP (JG)	PLASTIC DIP (P)			
0°C to 70°C	5 mV	TLC3702CD	—	—	TLC3702CP			
-40°C to 85°C	5 mV	TLC3702ID	_	_	TLC3702IP			
–55°C to 125°C	5 mV	TLC3702MD	TLC3702MFK	TLC3702MJG	—			

The D package is available taped and reeled. Add R suffix to the device type (e.g., TLC3702CDR).

# functional block diagram (each comparator)



# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{DD}$ (see Note 1) Differential input voltage, $V_{ID}$ (see Note 2) Input voltage range, $V_{I}$ Output voltage range, $V_{O}$ Input current, $I_{I}$ Output current, $I_{O}$ (each output) Total supply current into $V_{DD}$	
Total current out of GND	
Continuous total power dissipation	. See Dissipation Rating Table
Operating free-air temperature range, $T_A$ : TLC3702C	$0^{\circ}C$ to $70^{\circ}C$
Operating free-air temperature range, T <sub>A</sub> : TLC3702C TLC3702I	
	–40°C to 85°C
TLC3702I	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential voltages, are with respect to network ground.

2. Differential voltages are at IN+ with respect to IN-.



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	DISSIPATION RATING TABLE							
PACKAGE	$T_A \le 25^{\circ}C$ DERATINGPOWER RATINGABOVE T		T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING	T <sub>A</sub> = 125°C POWER RATING			
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW			
FK	1375 mW	11.0 mW/°C	880 mW	715 mW	275 mW			
JG	1050 mW	8.4 mW/°C	672 mW	546 mW	210 mW			
Р	1000 mW	8.0 mW/°C	640 mW	520 mW	N/A			

# recommended operating conditions

	TLC3702C			UNIT
	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>DD</sub>	3	5	16	V
Common-mode input voltage, VIC	- 0.2		V <sub>DD</sub> – 1.5	V
High-level output current, I <sub>OH</sub>			-20	mA
Low-level output current, IOL			20	mA
Operating free-air temperature, T <sub>A</sub>	0		70	°C

# electrical characteristics at specified operating free-air temperature, $V_{DD}$ = 5 V (unless otherwise noted)

PARAMETER		TEAT CONDITIONAL	T.	TLC3	702C		
	PARAMETER	TEST CONDITIONS <sup>†</sup>	Τ <sub>Α</sub>	MIN	TYP	MAX	UNIT
VIO	Input offset voltage	$V_{DD} = 5 V \text{ to } 10 V,$ $V_{IC} = V_{ICR} min,$	25°C		1.2	5	mV
10	input onest voltage	See Note 3	0°C to 70°C			6.5	
lie	Input offset current	V <sub>IC</sub> = 2.5 V	25°C		1		pА
ΙΟ	input onset current	V  C = 2.3 V	70°C			0.3	nA
lin.	Input bias current	V <sub>IC</sub> = 2.5 V	25°C		5		pА
IB	input bias current	VIC = 2.3 V	70°C			0.6	nA
Vien	Common mode input voltage range		25°C	0 to V <sub>DD</sub> – 1			V
VICR	Common-mode input voltage range		0°C to 70°C	0 to V <sub>DD</sub> – 1.5			v
			25°C		84		
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}min$	70°C		84		dB
			0°C		84		
			25°C		85		
k <sub>SVR</sub>	Supply-voltage rejection ratio	$V_{DD} = 5 V \text{ to } 10 V$	70°C		85	5 dB	
			0°C		85		
Val	High-level output voltage	V <sub>ID</sub> = 1 V,	25°C	4.5	4.7		V
VOH	High-level output voltage	$I_{OH} = -4 \text{ mA}$	70°C	4.3			v
Vai		$V_{ID} = -1 V,$	25°C		210	300	mV
VOL	Low-level output voltage	$I_{OH} = 4 \text{ mA}$	70°C			375	mv
	Supply current (both comparators)	Outputs low No load	25°C		18	40	
IDD	Supply current (both comparators)	Outputs low, No load	0°C to 70°C			50	μA

<sup>†</sup> All characteristics are measured with zero common-mode voltage unless otherwise noted.

NOTE 3: The offset voltage limits given are the maximum values required to drive the output up to 4.5 V or down to 0.3 V.



# recommended operating conditions

	TLC3702I			UNIT
	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>DD</sub>	3	5	16	V
Common-mode input voltage, V <sub>IC</sub>	-0.2		V <sub>DD</sub> – 1.5	V
High-level output current, I <sub>OH</sub>			-20	mA
Low-level output current, I <sub>OL</sub>			20	mA
Operating free-air temperature, T <sub>A</sub>	-40		85	°C

# electrical characteristics at specified operating free-air temperature, $V_{\text{DD}}$ = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONIST	-	TLC3702I			
		TEST CONDITIONS <sup>†</sup>	TA	MIN	TYP	MAX	UNIT
N/		V <sub>DD</sub> = 5 V to 10 V,	25°C		1.2	5	
VIO	Input offset voltage	$V_{IC} = V_{ICR}$ min, See Note 3	–40°C to 85°C			7	mV
lio.	Input offset current	$V_{10} = 25 V_{10}$	25°C		1		pА
IIO	input onset current	V <sub>IC</sub> = 2.5 V	85°C			1	nA
lun.	Input biog ourrept	$\lambda = 25 \lambda$	25°C		5		pА
IВ	Input bias current	V <sub>IC</sub> = 2.5 V	85°C			2	nA
VICR			25°C	0 to V <sub>DD</sub> – 1			Ň
	Common-mode input voltage range		–40°C to 85°C	0 to V <sub>DD</sub> – 1.5			V
			25°C		84		
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}min$	85°C		84		dB
			-40°C		83		
			25°C		85		
<b>k</b> SVR	Supply-voltage rejection ratio	$V_{DD} = 5 V \text{ to } 10 V$	85°C		85		dB
			-40°C		83		
Varia	Lich lovel entruit voltage		25°C	4.5	4.7		V
VOH	High-level output voltage	$V_{ID} = 1 V$ , $I_{OH} = -4 mA$	85°C	4.3			v
Va		$1/10 - 1/1 - 1011 - 4 m^{1}$	25°C		210	300	mV
VOL	Low-level output voltage	$V_{ID} = -1 V$ , $I_{OH} = -4 mA$	85°C			400	IIIV
	Supply current (both comparators)	Outputs low, No load	25°C		18	40	μA
DD	Supply current (both comparators)	Outputs low, No load	–40°C to 85°C			65	μΑ

<sup>†</sup> All characteristics are measured with zero common-mode voltage unless otherwise noted.

NOTE 3. The offset voltage limits given are the maximum values required to drive the output up to 4.5 V or down to 0.3 V.



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# recommended operating conditions

	TLC3702M			UNIT
	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>DD</sub>	4	5	16	V
Common-mode input voltage, V <sub>IC</sub>	0		V <sub>DD</sub> – 1.5	V
High-level output current, I <sub>OH</sub>			- 20	mA
Low-level output current, I <sub>OL</sub>			20	mA
Operating free-air temperature, T <sub>A</sub>	- 55		125	°C

electrical characteristics at specified operating free-air temperature, V <sub>DD</sub> = 5 V (unless otherwise	è
noted)	

	PARAMETER TEST CONDITIONS		- <b>-</b>	TLC	3702M		LINUT
	PARAMETER	TEST CONDITIONS <sup>†</sup>	TA	MIN	TYP	MAX	UNIT
Vie	logut offect veltere	V <sub>DD</sub> = 5 V to 10 V,	25°C		1.2	5	~~\/
VIO	Input offset voltage	$V_{IC} = V_{ICR}$ min, See Note 3	–55°C to 125°C			10	mV
lie	Input offset current	V <sub>IC</sub> = 2.5 V	25°C		1		pА
IIO	input onset current	VIC = 2.3 V	125°C			15	nA
lin.	Input bias current	$\lambda = 25 \lambda$	25°C		5		pА
IВ	input bias current	V <sub>IC</sub> = 2.5 V	125°C			30	nA
. <i>.</i>			25°C	0 to V <sub>DD</sub> – 1			V
VICR	Common-mode input voltage range		–55°C to 125°C	0 to V <sub>DD</sub> – 1.5			v
			25°C		84		
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}min$	125°C		83		dB
			–55°C		82		
			25°C		85		
<sup>k</sup> SVR	Supply-voltage rejection ratio	$V_{DD} = 5 V \text{ to } 10 V$	125°C		85		dB
			– 55°C		82		
Val	High-level output voltage	$V_{ID} = 1 V$ , $I_{OH} = -4 mA$	25°C	4.5	4.7		V
Vон	riigh-level ouput voltage	V D = 1.0, $IOH = -4.11A$	125°C	4.2			v
Voi	Low-level output voltage	$V_{ID} = -1 V$ , $I_{OH} = -4 mA$	25°C		210	300	mV
VOL		VID = -1 V, $VOH = -4$ IIIA	125°C			500	IIIV
	Supply current (both comparators)	Outputs low, No load	25°C		18	40	μA
DD			–55°C to 125°C			90	μΛ

 $\ensuremath{^\dagger}\xspace$  All characteristics are measured with zero common-mode voltage unless otherwise noted.

NOTE 3. The offset voltage limits given are the maximum values required to drive the output up to 4.5 V or down to 0.3 V.



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# switching characteristics, $V_{DD}$ = 5 V, $T_A$ = 25°C

	PARAMETER	TEST	TLC3702C, TLC3702I TLC3702M			UNIT	
			-	MIN	TYP	MAX	
			Overdrive = 2 mV		4.5		
			Overdrive = 5 mV		2.7		
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output $^{\dagger}$	f = 10 kHz, C <sub>L</sub> = 50 pF	Overdrive = 10 mV		1.9		μs
			Overdrive = 20 mV		1.4		
			Overdrive = 40 mV		1.1		
		VI = 1.4 V step at IN+		1.1			
			Overdrive = 2 mV		4		
				Overdrive = 5 mV		2.3	
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output $^{\dagger}$	$C_{L} = 50 \text{ pF}$	Overdrive = 10 mV		1.5		μs
			Overdrive = 20 mV		0.95		
			Overdrive = 40 mV		0.65		
		V <sub>I</sub> = 1.4 V ste	o at IN+		0.15		
t <sub>f</sub>	Fall time	f = 10 kHz, C <sub>L</sub> = 50 pF	Overdrive = 50 mV		50		ns
tr	Rise time	f = 10 kHz, C <sub>L</sub> = 50 pF	Overdrive = 50 mV		125		ns

<sup>†</sup> Simultaneous switching of inputs causes degradation in output response.



# PRINCIPLES OF OPERATION

#### LinCMOS<sup>™</sup> process

The LinCMOS<sup>™</sup> process is a linear polysilicon-gate CMOS process. Primarily designed for single-supply applications, LinCMOS<sup>™</sup> products facilitate the design of a wide range of high-performance analog functions from operational amplifiers to complex mixed-mode converters.

While digital designers are experienced with CMOS, MOS technologies are relatively new for analog designers. This short guide is intended to answer the most frequently asked questions related to the quality and reliability of LinCMOS<sup>™</sup> products. Further questions should be directed to the nearest TI field sales office.

#### electrostatic discharge

CMOS circuits are prone to gate oxide breakdown when exposed to high voltages even if the exposure is only for very short periods of time. Electrostatic discharge (ESD) is one of the most common causes of damage to CMOS devices. It can occur when a device is handled without proper consideration for environmental electrostatic charges, e.g., during board assembly. If a circuit in which one amplifier from a dual op amp is being used and the unused pins are left open, high voltages tend to develop. If there is no provision for ESD protection, these voltages may eventually punch through the gate oxide and cause the device to fail. To prevent voltage buildup, each pin is protected by internal circuitry.

Standard ESD-protection circuits safely shunt the ESD current by providing a mechanism whereby one or more transistors break down at voltages higher than the normal operating voltages but lower than the breakdown voltage of the input gate. This type of protection scheme is limited by leakage currents which flow through the shunting transistors during normal operation after an ESD voltage has occurred. Although these currents are small, on the order of tens of nanoamps, CMOS amplifiers are often specified to draw input currents as low as tens of picoamps.

To overcome this limitation, TI design engineers developed the patented ESD-protection circuit shown in Figure 1. This circuit can withstand several successive 2-kV ESD pulses, while reducing or eliminating leakage currents that may be drawn through the input pins. A more detailed discussion of the operation of the TI ESD-protection circuit is presented on the next page.

All input and output pins on LinCMOS<sup>™</sup> and Advanced LinCMOS<sup>™</sup> products have associated ESD-protection circuitry that undergoes qualification testing to withstand 2000 V discharged from a 100-pF capacitor through a 1500-Ω resistor (human body model) and 200 V from a 100-pF capacitor with no current-limiting resistor (charged device model). These tests simulate both operator and machine handling of devices during normal test and assembly operations.

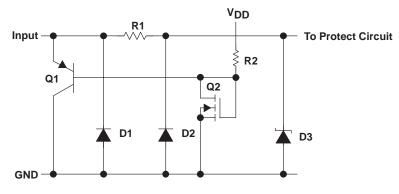


Figure 1. LinCMOS<sup>™</sup> ESD-Protection Schematic

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# PRINCIPLES OF OPERATION

### input protection circuit operation

Texas Instruments patented protection circuitry allows for both positive- and negative-going ESD transients. These transients are characterized by extremely fast rise times and usually low energies, and can occur both when the device has all pins open and when it is installed in a circuit.

### positive ESD transients

Initial positive charged energy is shunted through Q1 to V<sub>SS</sub>. Q1 turns on when the voltage at the input rises above the voltage on the V<sub>DD</sub> pin by a value equal to the V<sub>BE</sub> of Q1. The base current increases through R2 with input current as Q1 saturates. The base current through R2 forces the voltage at the drain and gate of Q2 to exceed its threshold level (V<sub>T</sub> ~ 22 to 26 V) and turn Q2 on. The shunted input current through Q1 to V<sub>SS</sub> is now shunted through the n-channel enhancement-type MOSFET Q2 to V<sub>SS</sub>. If the voltage on the input pin continues to rise, the breakdown voltage of the zener diode D3 is exceeded and all remaining energy is dissipated in R1 and D3. The breakdown voltage of D3 is designed to be 24 V to 27 V, which is well below the gate-oxide voltage of the circuit to be protected.

### negative ESD transients

The negative charged ESD transients are shunted directly through D1. Additional energy is dissipated in R1 and D2 as D2 becomes forward biased. The voltage seen by the protected circuit is -0.3 V to -1 V (the forward voltage of D1 and D2).

### circuit-design considerations

LinCMOS<sup>TM</sup> products are being used in actual circuit environments that have input voltages that exceed the recommended common-mode input voltage range and activate the input protection circuit. Even under normal operation, these conditions occur during circuit power up or power down, and in many cases, when the device is being used for a signal conditioning function. The input voltages can exceed V<sub>ICR</sub> and not damage the device only if the inputs are current limited. The recommended current limit shown on most product data sheets is  $\pm 5$  mA. Figure 2 and Figure 3 show typical characteristics for input voltage versus input current.

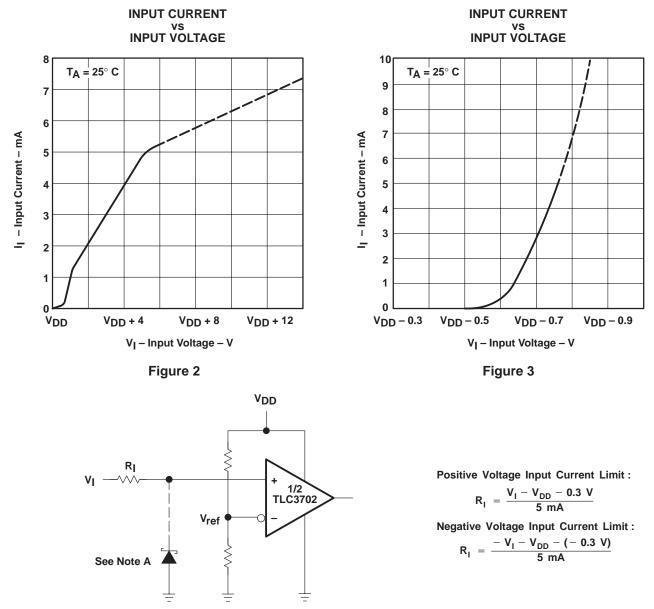
Normal operation and correct output state can be expected even when the input voltage exceeds the positive supply voltage. Again, the input current should be externally limited even though internal positive current limiting is achieved in the input protection circuit by the action of Q1. When Q1 is on, it saturates and limits the current to approximately 5-mA collector current by design. When saturated, Q1 base current increases with input current. This base current is forced into the V<sub>DD</sub> pin and into the device I<sub>DD</sub> or the V<sub>DD</sub> supply through R2 producing the current limiting effects shown in Figure 2. This internal limiting lasts only as long as the input voltage is below the V<sub>T</sub> of Q2.

When the input voltage exceeds the negative supply voltage, normal operation is affected and output voltage states may not be correct. Also, the isolation between channels of multiple devices (duals and quads) can be severely affected. External current limiting must be used since this current is directly shunted by D1 and D2 and no internal limiting is achieved. If normal output voltage states are required, an external input voltage clamp is required (see Figure 4).



# **PRINCIPLES OF OPERATION**

# circuit-design considerations (continued)



NOTE A: If the correct input state is required when the negative input exceeds GND, a Schottky clamp is required.

### Figure 4. Typical Input Current-Limiting Configuration for a LinCMOS™ Comparator



# PARAMETER MEASUREMENT INFORMATION

The TLC3702 contains a digital output stage which, if held in the linear region of the transfer curve, can cause damage to the device. Conventional operational amplifier/comparator testing incorporates the use of a servo loop which is designed to force the device output to a level within this linear region. Since the servo-loop method of testing cannot be used, we offer the following alternatives for measuring parameters such as input offset voltage, common-mode rejection, etc.

To verify that the input offset voltage falls within the limits specified, the limit value is applied to the input as shown in Figure 5(a). With the noninverting input positive with respect to the inverting input, the output should be high. With the input polarity reversed, the output should be low.

A similar test can be made to verify the input offset voltage at the common-mode extremes. The supply voltages can be slewed to provide greater accuracy, as shown in Figure 5(b) for the  $V_{ICR}$  test. This slewing is done instead of changing the input voltages.

A close approximation of the input offset voltage can be obtained by using a binary search method to vary the differential input voltage while monitoring the output state. When the applied input voltage differential is equal, but opposite in polarity, to the input offset voltage, the output changes states.

Figure 6 illustrates a practical circuit for direct dc measurement of input offset voltage that does not bias the comparator in the linear region. The circuit consists of a switching mode servo loop in which IC1a generates a triangular waveform of approximately 20-mV amplitude. IC1b acts as a buffer, with C2 and R4 removing any residual dc offset. The signal is then applied to the inverting input of the comparator under test, while the noninverting input is driven by the output of the integrator formed by IC1c through the voltage divider formed by R8 and R9. The loop reaches a stable operating point when the output of the comparator under test has a duty cycle of exactly 50%, which can only occur when the incoming triangle wave is sliced symmetrically or when the voltage at the noninverting input exactly equals the input offset voltage.

Voltage dividers R8 and R9 provide an increase in input offset voltage by a factor of 100 to make measurement easier. The values of R5, R7, R8, and R9 can significantly influence the accuracy of the reading; therefore, it is suggested that their tolerance level be one percent or lower.

Measuring the extremely low values of input current requires isolation from all other sources of leakage current and compensation for the leakage of the test socket and board. With a good picoammeter, the socket and board leakage can be measured with no device in the socket. Subsequently, this open socket leakage value can be subtracted from the measurement obtained with a device in the socket to obtain the actual input current of the device.

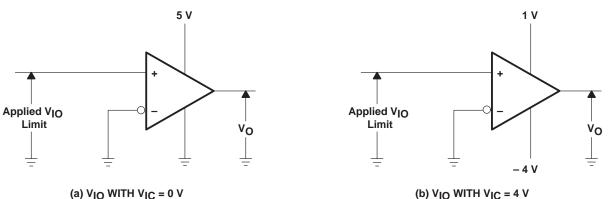
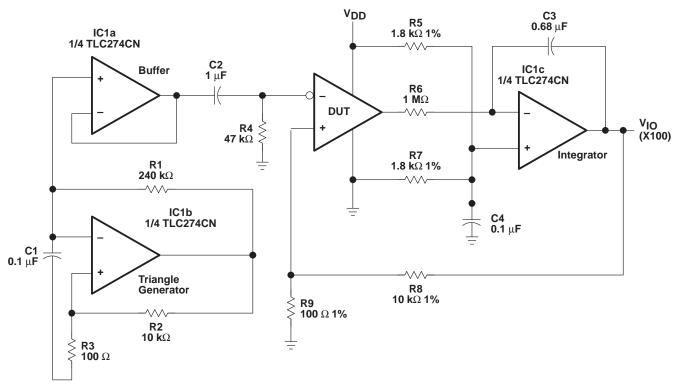


Figure 5. Method for Verifying That Input Offset Voltage Is Within Specified Limits



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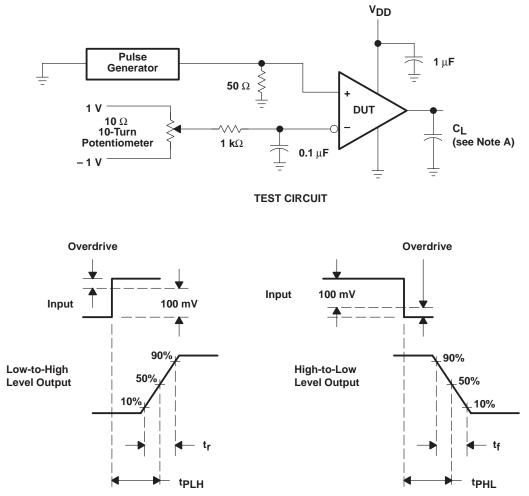


# PARAMETER MEASUREMENT INFORMATION



Response time is defined as the interval between the application of an input step function and the instant when the output reaches 50% of its maximum value. Response time for the low-to-high-level output is measured from the leading edge of the input pulse, while response time for the high-to-low-level output is measured from the trailing edge of the input pulse. Response time measurement at low input signal levels can be greatly affected by the input offset voltage. The offset voltage should be balanced by the adjustment at the inverting input as shown in Figure 7, so that the circuit is just at the transition point. A low signal, for example 105-mV or 5-mV overdrive, causes the output to change state.





PARAMETER MEASUREMENT INFORMATION

VOLTAGE WAVEFORMS

NOTE A:  $C_L$  includes probe and jig capacitance.

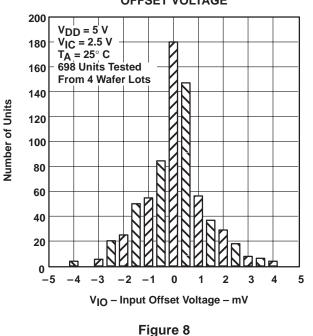




# **TYPICAL CHARACTERISTICS<sup>†</sup>**

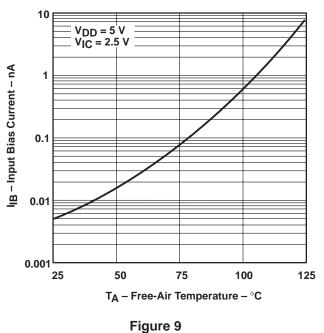
			FIGURE
VIO	Input offset voltage	Distribution	8
I <sub>IB</sub>	Input bias current	vs Free-air temperature	9
CMRR	Common-mode rejection ratio	vs Free-air temperature	10
<b>k</b> SVR	Supply-voltage rejection ratio	vs Free-air temperature	11
VOH	High-level output current	vs Free-air temperature vs High-level output current	12 13
VOL	Low-level output voltage	vs Low-level output current vs Free-air temperature	14 15
t <sub>t</sub>	Transition time	vs Load capacitance	16
	Supply current response	vs Time	17
	Low-to-high-level output response	Low-to-high level output propagation delay time	18
	High-to-low level output response	High-to-low level output propagation delay time	19
<sup>t</sup> PLH	Low-to-high level output propagation delay time	vs Supply voltage	20
<sup>t</sup> PHL	High-to-low level output propagation delay time	vs Supply voltage	21
IDD	Supply current	vs Frequency vs Supply voltage vs Free-air temperature	22 23 24

### **Table of Graphs**



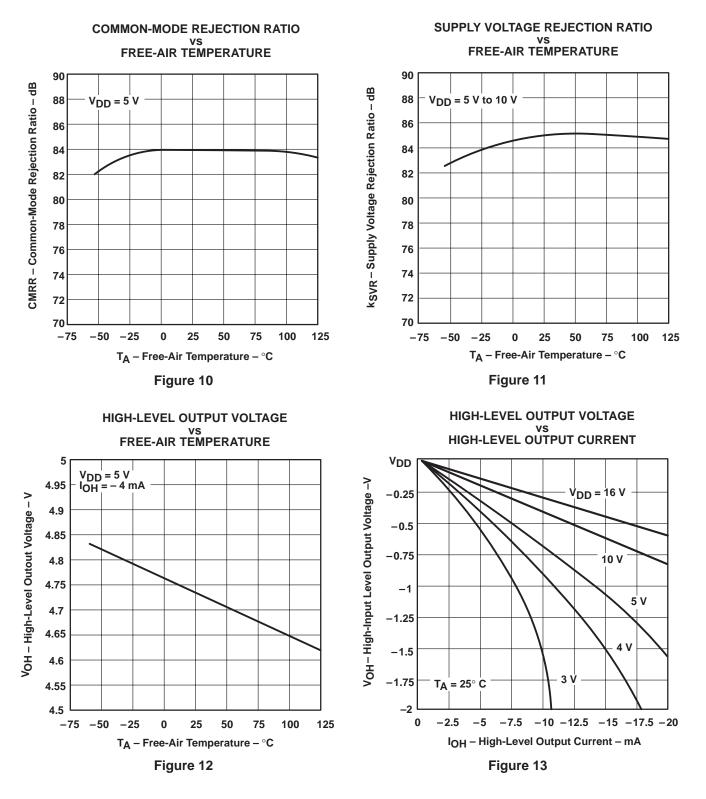
#### DISTRIBUTION OF INPUT OFFSET VOLTAGE

#### INPUT BIAS CURRENT vs FREE-AIR TEMPERATURE



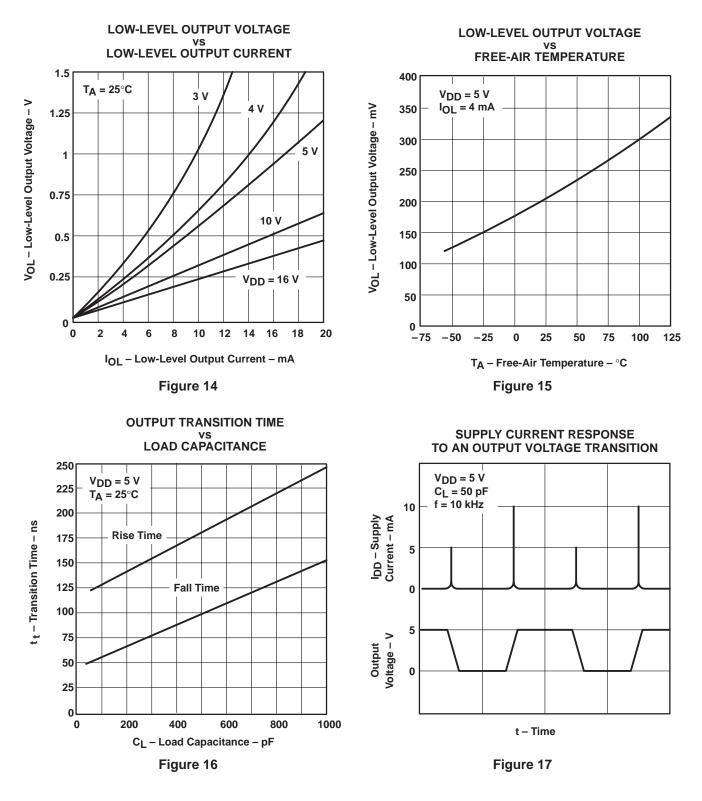




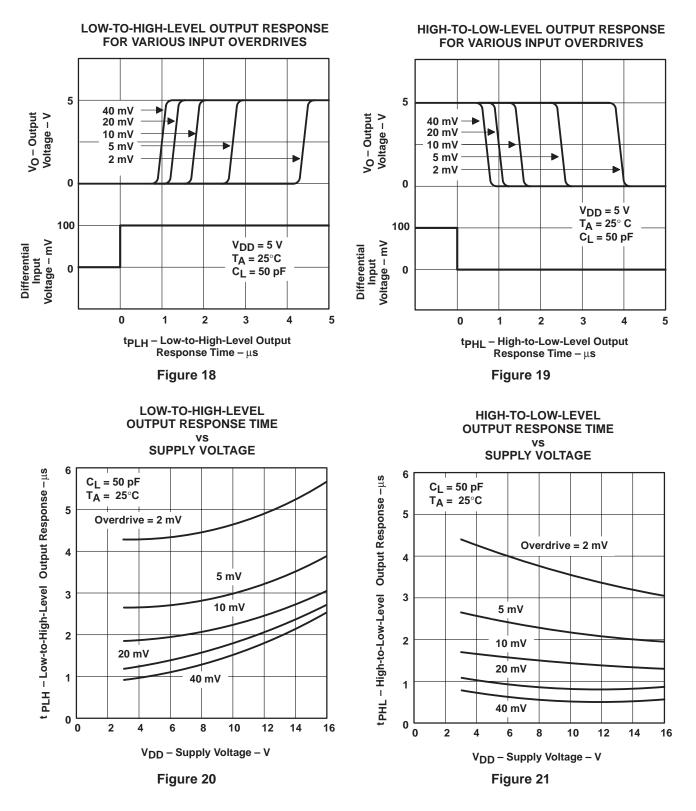




# **TYPICAL CHARACTERISTICS<sup>†</sup>**







# TYPICAL CHARACTERISTICS



#### AVERAGE SUPPLY CURRENT SUPPLY CURRENT (PER COMPARATOR) vs SUPPLY VOLTAGE vs FREQUENCY 40 10000 **Outputs Low** – 55°C T<sub>A</sub> = $T_A = 25^{\circ}C$ No Loads 35 $T_A = -40^{\circ}C$ $C_L = 50 \text{ pF}$ V<sub>DD</sub> = 16 V VDD- Supply Current - µA VDD- Supply Current -µA 30 1000 25 – 25°C TA = 10 V 20 5 V 15 $T_A = -125^{\circ}C$ 100 T<sub>A</sub> = 85°C 10 5 3 V 0 10 O 1 2 3 4 5 6 7 8 0.01 0.1 10 100 1 f - Frequency - kHz V<sub>DD</sub> – Supply Voltage – V Figure 22 Figure 23 SUPPLY CURRENT vs FREE-AIR TEMPERATURE 30 $V_{DD} = 5 V$ No Load 25 IDD – Supply Current –µA 20 **Outputs Low** 15 10 **Outputs High** 5 0 -50 50 75 -75 -25 0 25 100 125 T<sub>A</sub> – Free-Air Temperature – °C Figure 24

# **TYPICAL CHARACTERISTICS<sup>†</sup>**



# **APPLICATION INFORMATION**

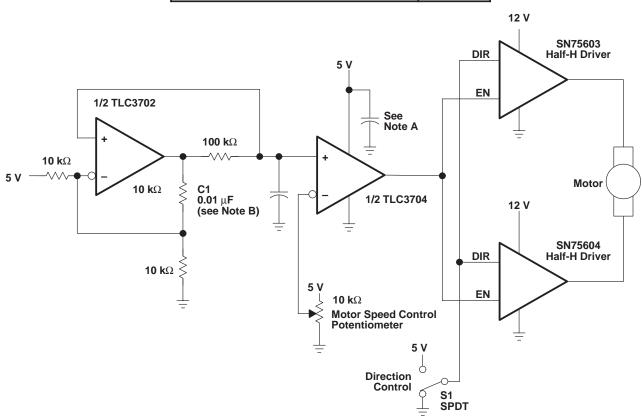
The inputs should always remain within the supply rails in order to avoid forward biasing the diodes in the electrostatic discharge (ESD) protection structure. If either input exceeds this range, the device is not damaged as long as the input is limited to less than 5 mA. To maintain the expected output state, the inputs must remain within the common-mode range. For example, at 25°C with  $V_{DD} = 5$  V, both inputs must remain between -0.2 V and 4 V to ensure proper device operation.

To ensure reliable operation, the supply should be decoupled with a capacitor  $(0.1 \,\mu\text{F})$  that is positioned as close to the device as possible.

The TLC3702 has internal ESD-protection circuits that prevent functional failures at voltages up to 2000 V as tested under MIL-STD-883C, Method 3015.2; however, care should be exercised in handling these devices as exposure to ESD may result in the degradation of the device parametric performance.

	FIGURE
Pulse-width-modulated motor speed controller	25
Enhanced supply supervisor	26
Two-phase nonoverlapping clock generator	27
Micropower switching regulator	28

**Table of Applications** 

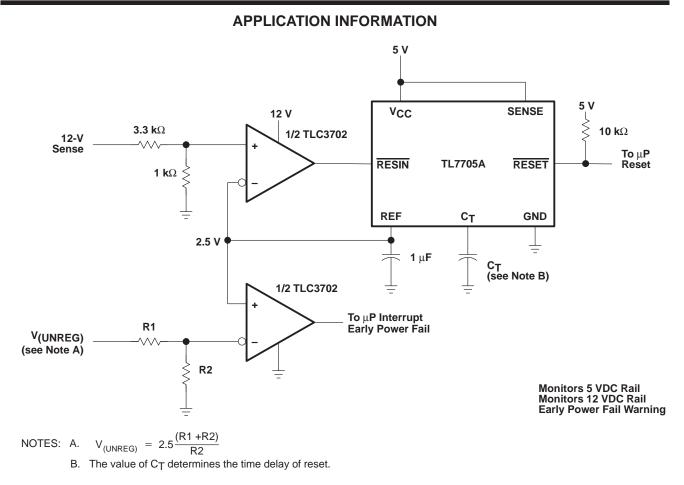


#### NOTES: A. The recommended minimum capacitance is 10 µF to eliminate common ground switching noise. B. Adjust C1 for change in oscillator frequency.

# Figure 25. Pulse-Width-Modulated Motor Speed Controller



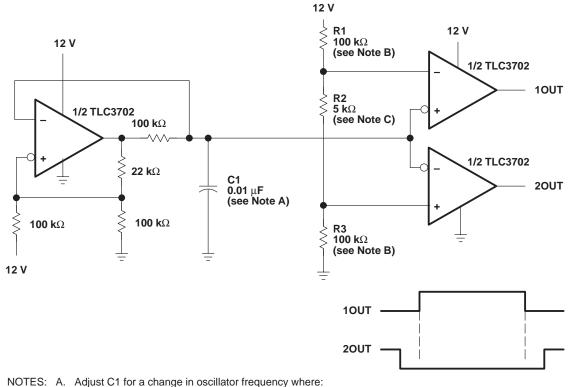
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# **APPLICATION INFORMATION**

NOTES: A. Adjust C1 for a change in oscillator frequency where:

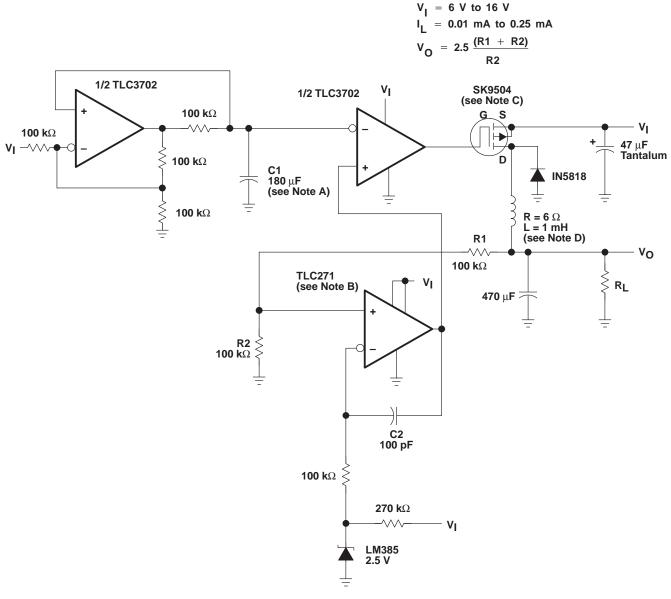
- 1/f = 1.85(100 kΩ)C1
- B. Adjust R1 and R3 to change duty cycle
- C. Adjust R2 to change deadtime

#### Figure 27. Two-Phase Nonoverlapping Clock Generator



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# **APPLICATION INFORMATION**



- NOTES: A. Adjust C1 for a change in oscillator frequency
  - B. TLC271 Tie pin 8 to pin 7 for low bias operation
  - C. SK9504 VDS = 40 V
    - IDS = 1 A
  - D. To achieve microampere current drive, the inductance of the circuit must be increased.

Figure 28. Micropower Switching Regulator

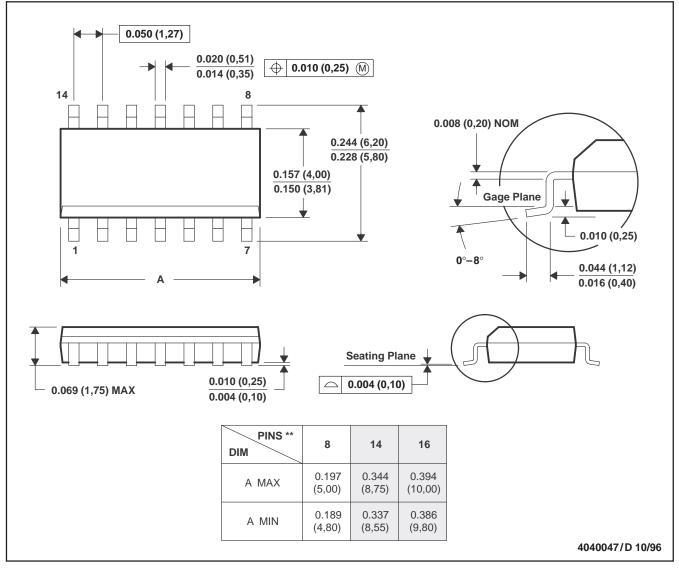


**MECHANICAL DATA** 

### D (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE PACKAGE

#### 14 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

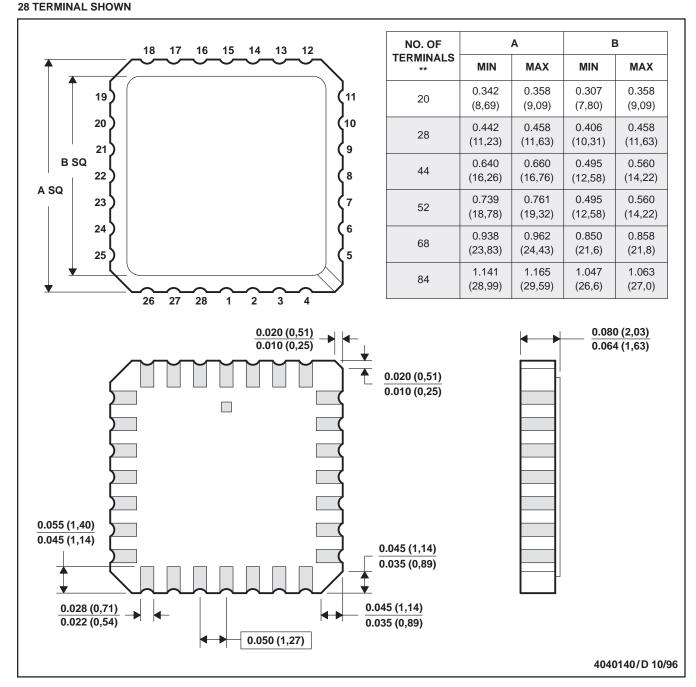
D. Falls within JEDEC MS-012



### MECHANICAL DATA

### LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N\*\*)



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



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JG (R-GDIP-T8)

**MECHANICAL DATA** 

**CERAMIC DUAL-IN-LINE PACKAGE** 

0.400 (10,20) 0.355 (9,00) 0.280 (7,11) 0.245 (6,22) 1 4 0.065 (1,65) 0.045 (1,14) 0.310 (7,87) 0.020 (0,51) MIN 0.290 (7,37) 0.200 (5,08) MAX **Seating Plane** 0.130 (3,30) MIN 0.063 (1,60) 0°–15° 0.015 (0,38) 0.023 (0,58) 0.015 (0,38) 0.100 (2,54) 0.014 (0,36) 0.008 (0,20) 4040107/C 08/96

NOTES: A. All linear dimensions are in inches (millimeters).

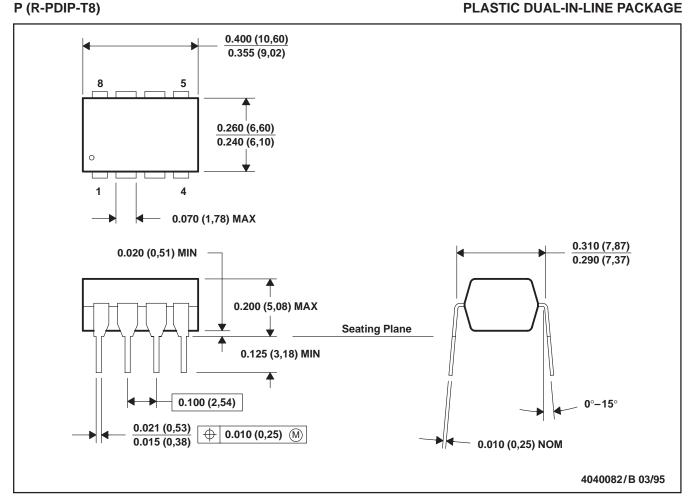
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL-STD-1835 GDIP1-T8



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**MECHANICAL DATA** 

#### PLASTIC DUAL-IN-LINE PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MS-001



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